

## 1 Mbit SPI Serial SRAM with Battery Backup and SDI Interface

### Device Selection Table

| Part Number | Vcc Range | Dual I/O (SDI) | Battery Backup | Max. Clock Frequency | Packages  |
|-------------|-----------|----------------|----------------|----------------------|-----------|
| 23LCV1024   | 2.5-5.5V  | Yes            | Yes            | 20 MHz               | SN, ST, P |

### Features:

- SPI-Compatible Bus Interface:
  - 20 MHz Clock rate
  - SPI/SDI mode
- Low-Power CMOS Technology:
  - Read Current: 3 mA at 5.5V, 20 MHz
  - Standby Current: 4  $\mu$ A at +85°C
- Unlimited Read and Write Cycles
- External Battery Backup Support
- Zero Write Time
- 128K x 8-bit Organization:
  - 32-byte page
- Byte, Page and Sequential mode for Reads and Writes
- High Reliability
- Temperature Range Supported:
  - Industrial (I): -40°C to +85°C
- Pb-Free and RoHS Compliant, Halogen Free
- 8-Lead SOIC, TSSOP and PDIP Packages

### Pin Function Table

| Name            | Function                     |
|-----------------|------------------------------|
| $\overline{CS}$ | Chip Select Input            |
| SO/SIO1         | Serial Output/SDI Pin        |
| Vss             | Ground                       |
| SI/SIO0         | Serial Input/SDI Pin         |
| SCK             | Serial Clock                 |
| VBAT            | External Backup Supply Input |
| Vcc             | Power Supply                 |

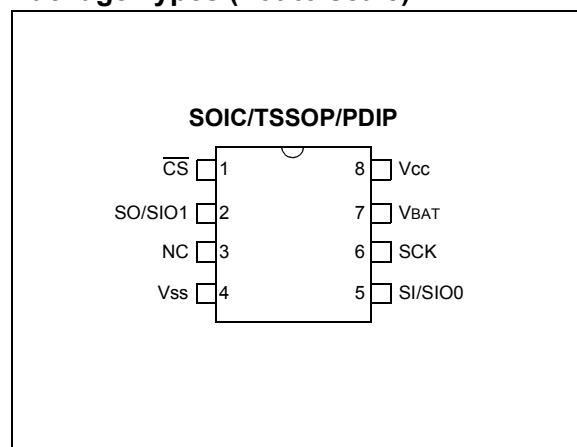
### Description:

The Microchip Technology Inc. 23LCV1024 is a 1 Mbit Serial SRAM device. The memory is accessed via a simple Serial Peripheral Interface (SPI) compatible serial bus. The bus signals required are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled through a Chip Select ( $\overline{CS}$ ) input. Additionally, SDI (Serial Dual Interface) is supported if your application needs faster data rates.

This device also supports unlimited reads and writes to the memory array, and supports data backup via an external battery/coin cell connected to VBAT (pin 7).

The 23LCV1024 is available in standard packages including 8-lead SOIC, PDIP and advanced 8-lead TSSOP.

### Package Types (not to scale)



# 23LCV1024

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings (†)

|                                         |                    |
|-----------------------------------------|--------------------|
| VCC.....                                | 6.5V               |
| All inputs and outputs w.r.t. VSS ..... | -0.3V to VCC +0.3V |
| Storage temperature .....               | -65°C to +150°C    |
| Ambient temperature under bias .....    | -40°C to +85°C     |

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for an extended period of time may affect device reliability.

**TABLE 1-1: DC CHARACTERISTICS**

| DC CHARACTERISTICS |          |                            | Industrial (I): TA = -40°C to +85°C |                     |          |       |                                                          |
|--------------------|----------|----------------------------|-------------------------------------|---------------------|----------|-------|----------------------------------------------------------|
| Param. No.         | Sym.     | Characteristic             | Min.                                | Typ. <sup>(1)</sup> | Max.     | Units | Test Conditions                                          |
| D001               | VCC      | Supply voltage             | 2.5                                 | —                   | 5.5      | V     | 23LCV1024                                                |
| D002               | VIH      | High-level input voltage   | .7 VCC                              | —                   | VCC +0.3 | V     |                                                          |
| D003               | VIL      | Low-level input voltage    | -0.3                                | —                   | 0.10xVCC | V     | 23LCV1024                                                |
| D004               | VOL      | Low-level output voltage   | —                                   | —                   | 0.2      | V     | IOL = 1 mA                                               |
| D005               | VOH      | High-level output voltage  | VCC -0.5                            | —                   | —        | V     | IOH = -400 µA                                            |
| D006               | IIi      | Input leakage current      | —                                   | —                   | ±1       | µA    | $\overline{CS} = VCC, V_{IN} = VSS \text{ OR } VCC$      |
| D007               | ILO      | Output leakage current     | —                                   | —                   | ±1       | µA    | $\overline{CS} = VCC, V_{OUT} = VSS \text{ OR } VCC$     |
| D008               | ICC Read | Operating current          | —                                   | 3                   | 10       | mA    | FCLK = 20 MHz; SO = 0, 5.5V                              |
| D009               | ICCS     | Standby current            | —                                   | 4                   | 10       | µA    | $\overline{CS} = VCC = 5.5V$ , Inputs tied to VCC or VSS |
| D010               | CINT     | Input capacitance          | —                                   | —                   | 7        | pF    | VCC = 0V, f = 1 MHz, Ta = 25°C<br>(Note 1)               |
| D011               | VDR      | RAM data retention voltage | —                                   | 1.0                 | —        | V     | (Note 2)                                                 |
| D012               | VTRIP    | VBAT Change Over           | 1.6                                 | 1.8                 | 2.0      | V     | Typical at Ta = 25°C<br>(Note 1)                         |
| D013               | VBAT     | VBAT Voltage Range         | 1.4                                 | —                   | 3.6      | V     | (Note 1)                                                 |
| D014               | IBAT     | VBAT Current               | —                                   | 1                   | —        | µA    | Typical at 2.5V, Ta = 25°C<br>(Note 1)                   |

**Note 1:** This parameter is periodically sampled and not 100% tested. Typical measurements taken at room temperature (25°C).

**2:** This is the limit to which VDD can be lowered without losing RAM data. This parameter is periodically sampled and not 100% tested.

TABLE 1-2: AC CHARACTERISTICS

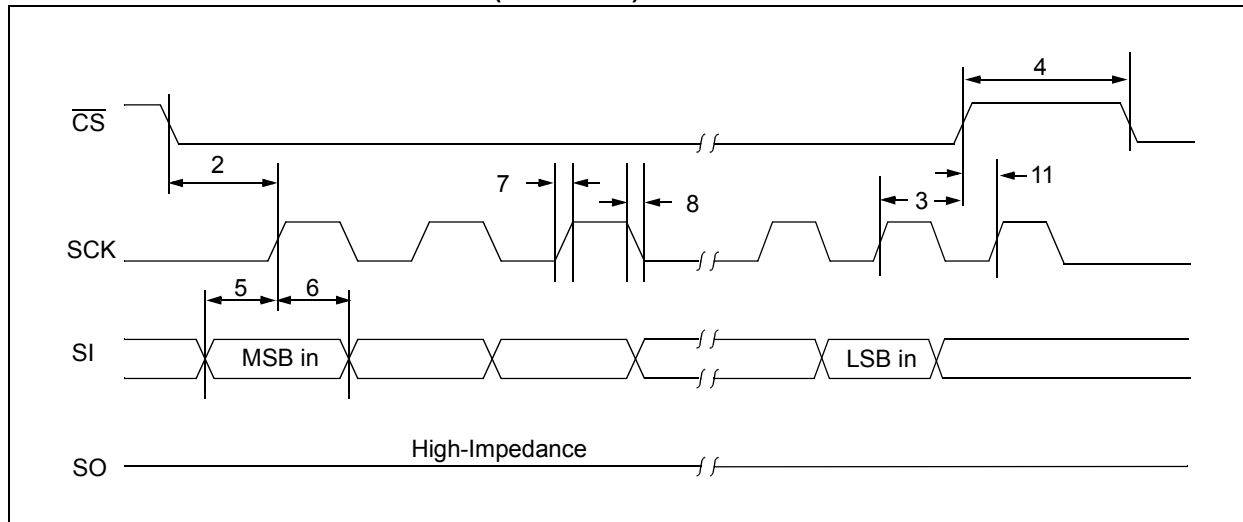
| AC CHARACTERISTICS |      |                              | Industrial (I): TA = -40°C to +85°C |      |       |                 |
|--------------------|------|------------------------------|-------------------------------------|------|-------|-----------------|
| Param. No.         | Sym. | Characteristic               | Min.                                | Max. | Units | Test Conditions |
| 1                  | FCLK | Clock frequency              | —                                   | 20   | MHz   |                 |
| 2                  | Tcss | $\overline{CS}$ setup time   | 25                                  | —    | ns    |                 |
| 3                  | Tcsh | $\overline{CS}$ hold time    | 50                                  | —    | ns    |                 |
| 4                  | TcSD | $\overline{CS}$ disable time | 25                                  | —    | ns    |                 |
| 5                  | Tsu  | Data setup time              | 10                                  | —    | ns    |                 |
| 6                  | THD  | Data hold time               | 10                                  | —    | ns    |                 |
| 7                  | TR   | CLK rise time                | —                                   | 20   | ns    | Note 1          |
| 8                  | TF   | CLK fall time                | —                                   | 20   | ns    | Note 1          |
| 9                  | THI  | Clock high time              | 25                                  | —    | ns    |                 |
| 10                 | TLO  | Clock low time               | 25                                  | —    | ns    |                 |
| 11                 | TCLD | Clock delay time             | 25                                  | —    | ns    |                 |
| 12                 | Tv   | Output valid from clock low  | —                                   | 25   | ns    |                 |
| 13                 | THO  | Output hold time             | 0                                   | —    | ns    | Note 1          |
| 14                 | TDis | Output disable time          | —                                   | 20   | ns    |                 |

**Note 1:** This parameter is periodically sampled and not 100% tested.

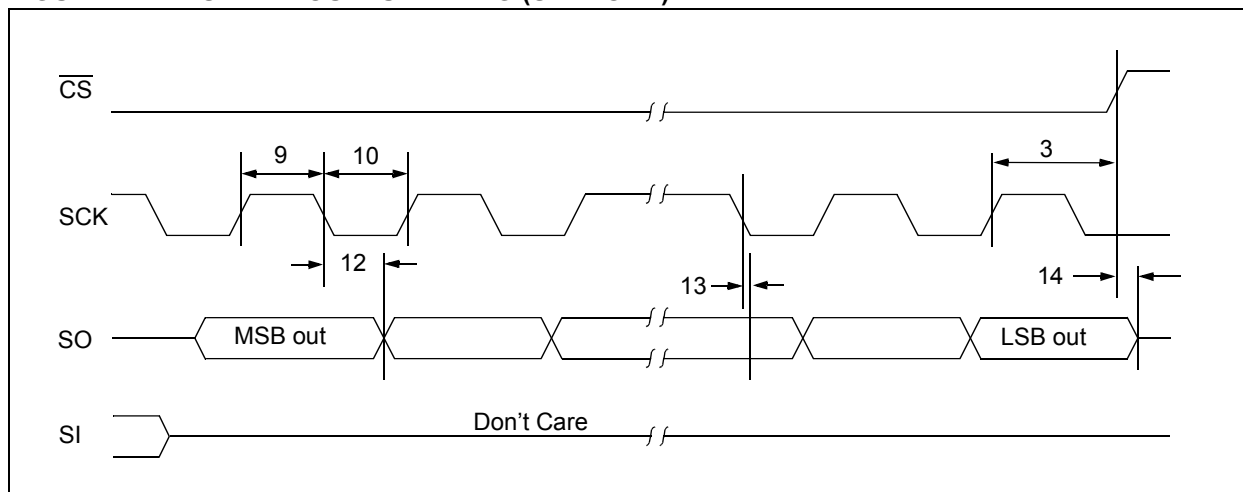
TABLE 1-3: AC TEST CONDITIONS

| AC Waveform:                        |                    |
|-------------------------------------|--------------------|
| Input pulse level                   | 0.1 Vcc to 0.9 Vcc |
| Input rise/fall time                | 5 ns               |
| Operating temperature               | -40°C to +85°C     |
| CL = 30 pF                          | —                  |
| Timing Measurement Reference Level: |                    |
| Input                               | 0.5 Vcc            |
| Output                              | 0.5 Vcc            |

**FIGURE 1-1: SERIAL INPUT TIMING (SPI MODE)**



**FIGURE 1-2: SERIAL OUTPUT TIMING (SPI MODE)**



## 2.0 FUNCTIONAL DESCRIPTION

### 2.1 Principles of Operation

The 23LCV1024 is an 1 Mbit Serial SRAM designed to interface directly with the Serial Peripheral Interface (SPI) port of many of today's popular microcontroller families, including Microchip's PIC® microcontrollers. It may also interface with microcontrollers that do not have a built-in SPI port by using discrete I/O lines programmed properly in firmware to match the SPI protocol. In addition, the 23LCV1024 is also capable of operating in SDI (or dual SPI) mode.

The 23LCV1024 contains an 8-bit instruction register. The device is accessed via the SI pin, with data being clocked in on the rising edge of SCK. The  $\overline{\text{CS}}$  pin must be low for the entire operation.

Table 2-1 contains a list of the possible instruction bytes and format for device operation. All instructions, addresses and data are transferred MSB first, LSB last.

### 2.2 Modes of Operation

The 23LCV1024 has three modes of operation that are selected by setting bits 7 and 6 in the MODE register. The modes of operation are Byte, Page and Burst.

**Byte Operation** – is selected when bits 7 and 6 in the MODE register are set to 00. In this mode, the read/write operations are limited to only one byte. The command followed by the 24-bit address is clocked into the device and the data to/from the device is transferred on the next eight clocks (Figure 2-1, Figure 2-2).

**Page Operation** – is selected when bits 7 and 6 in the MODE register are set to 10. The 23LCV1024 has 4096 pages of 32 bytes. In this mode, the read and write operations are limited to within the addressed page (the address is automatically incremented internally). If the data being read or written reaches the page boundary, then the internal address counter will increment to the start of the page (Figure 2-3, Figure 2-4).

**Sequential Operation** – is selected when bits 7 and 6 in the MODE register are set to 01. Sequential operation allows the entire array to be written to and read from. The internal address counter is automatically incremented and page boundaries are ignored. When the internal address counter reaches the end of the array, the address counter will roll over to 0x00000 (Figure 2-5, Figure 2-6).

### 2.3 Read Sequence

The device is selected by pulling  $\overline{\text{CS}}$  low. The 8-bit READ instruction is transmitted to the 23LCV1024 followed by the 24-bit address, with the first seven MSB's of the address being a "don't care" bit. After the correct READ instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin.

If operating in Sequential mode, the data stored in the memory at the next address can be read sequentially by continuing to provide clock pulses. The internal Address Pointer is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (1FFFFh), the address counter rolls over to address 00000h, allowing the read cycle to be continued indefinitely. The read operation is terminated by raising the  $\overline{\text{CS}}$  pin.

### 2.4 Write Sequence

Prior to any attempt to write data to the 23LCV1024, the device must be selected by bringing  $\overline{\text{CS}}$  low.

Once the device is selected, the Write command can be started by issuing a WRITE instruction, followed by the 24-bit address, with the first seven MSB's of the address being a "don't care" bit, and then the data to be written. A write is terminated by the  $\overline{\text{CS}}$  being brought high.

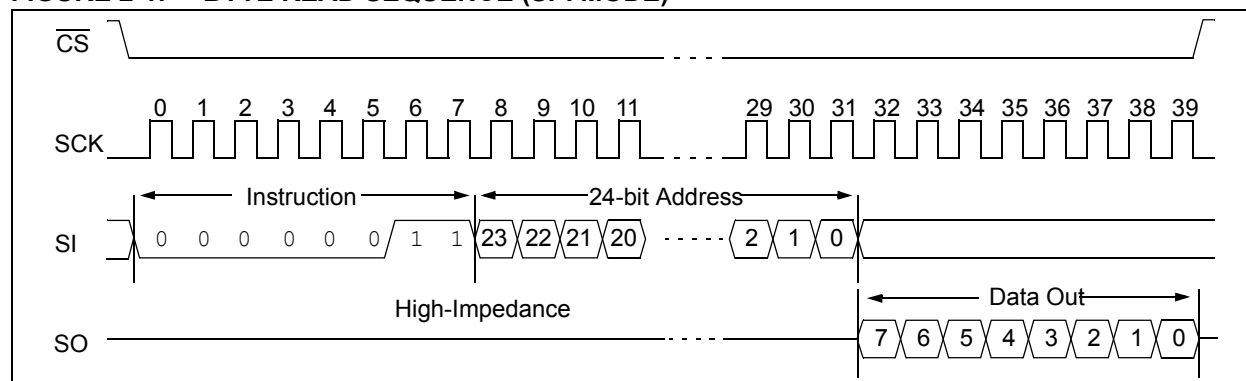
If operating in Page mode, after the initial data byte is shifted in, additional bytes can be shifted into the device. The Address Pointer is automatically incremented. This operation can continue for the entire page (32 bytes) before data will start to be overwritten.

If operating in Sequential mode, after the initial data byte is shifted in, additional bytes can be clocked into the device. The internal Address Pointer is automatically incremented. When the Address Pointer reaches the highest address (1FFFFh), the address counter rolls over to (00000h). This allows the operation to continue indefinitely, however, previous data will be overwritten.

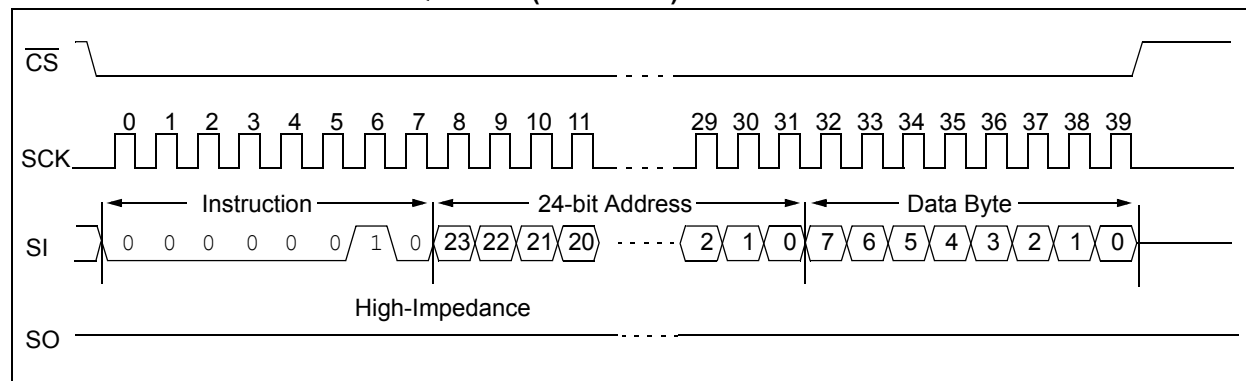
**TABLE 2-1: INSTRUCTION SET**

| Instruction Name | Instruction Format | Hex Code | Description                                               |
|------------------|--------------------|----------|-----------------------------------------------------------|
| READ             | 0000 0011          | 0x03     | Read data from memory array beginning at selected address |
| WRITE            | 0000 0010          | 0x02     | Write data to memory array beginning at selected address  |
| EDIO             | 0011 1011          | 0x3B     | Enter Dual I/O access                                     |
| RSTIO            | 1111 1111          | 0xFF     | Reset Dual I/O access                                     |
| RDMR             | 0000 0101          | 0x05     | Read Mode Register                                        |
| WRMR             | 0000 0001          | 0x01     | Write Mode Register                                       |

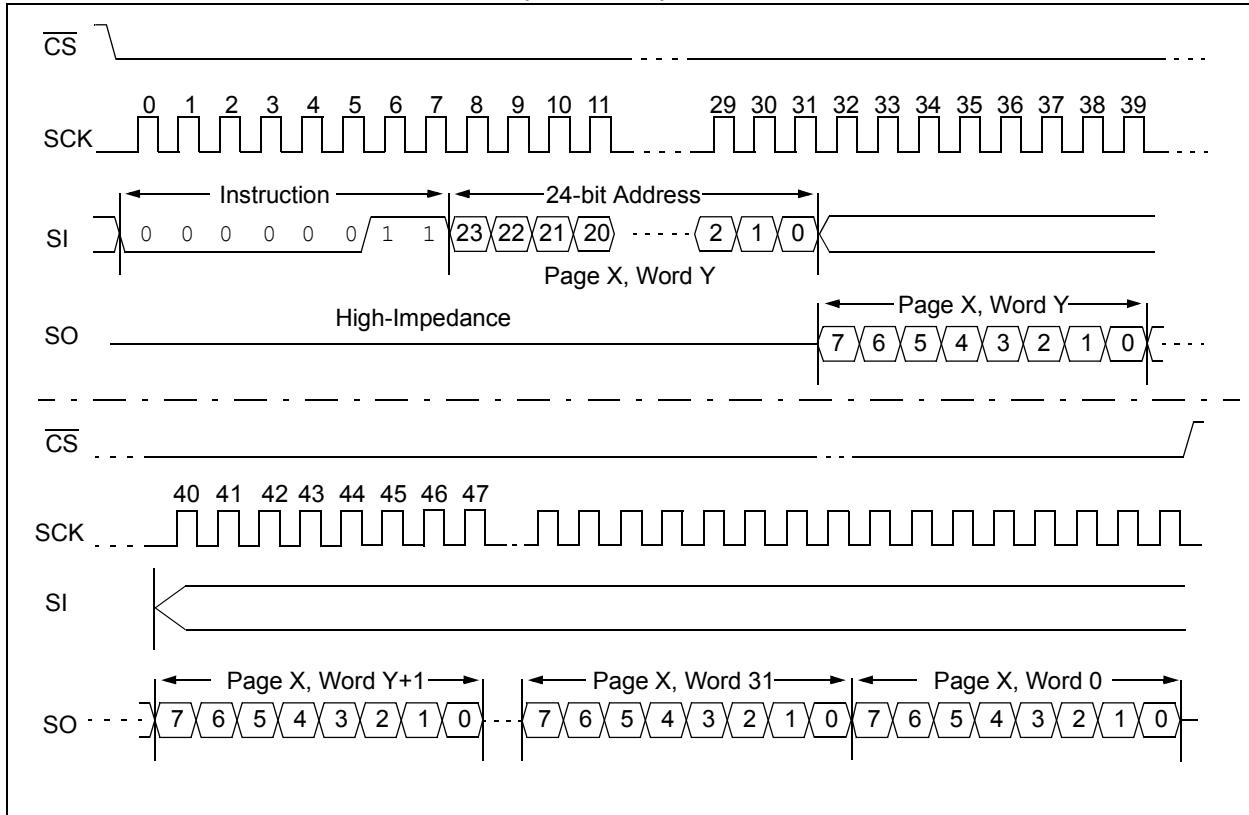
**FIGURE 2-1: BYTE READ SEQUENCE (SPI MODE)**



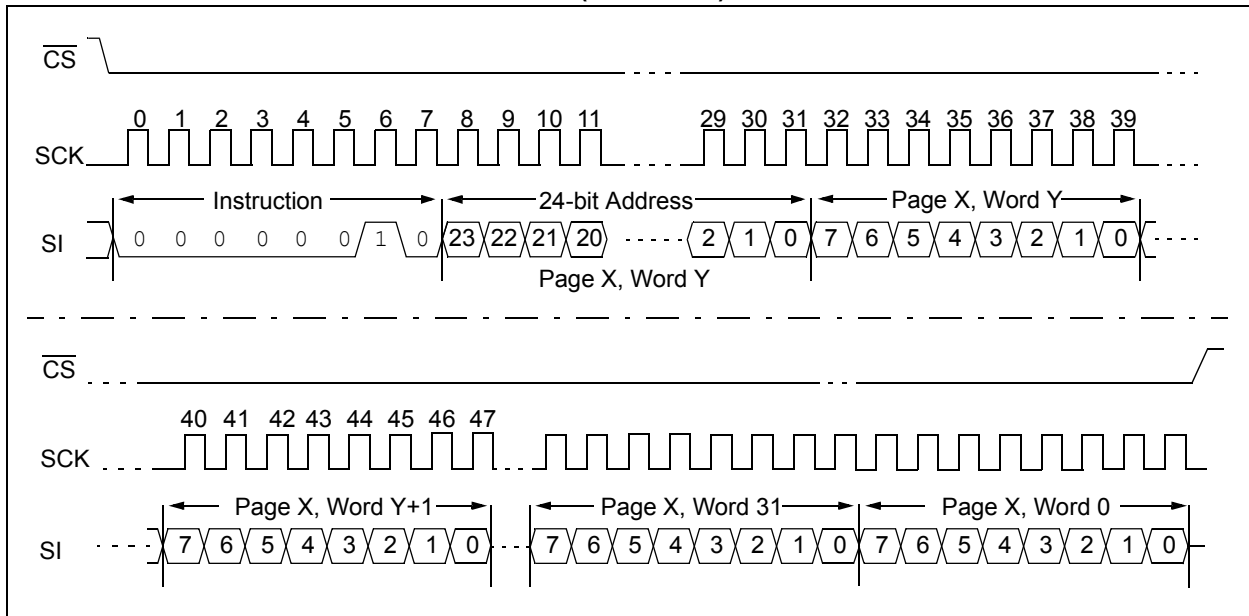
**FIGURE 2-2: BYTE WRITE SEQUENCE (SPI MODE)**



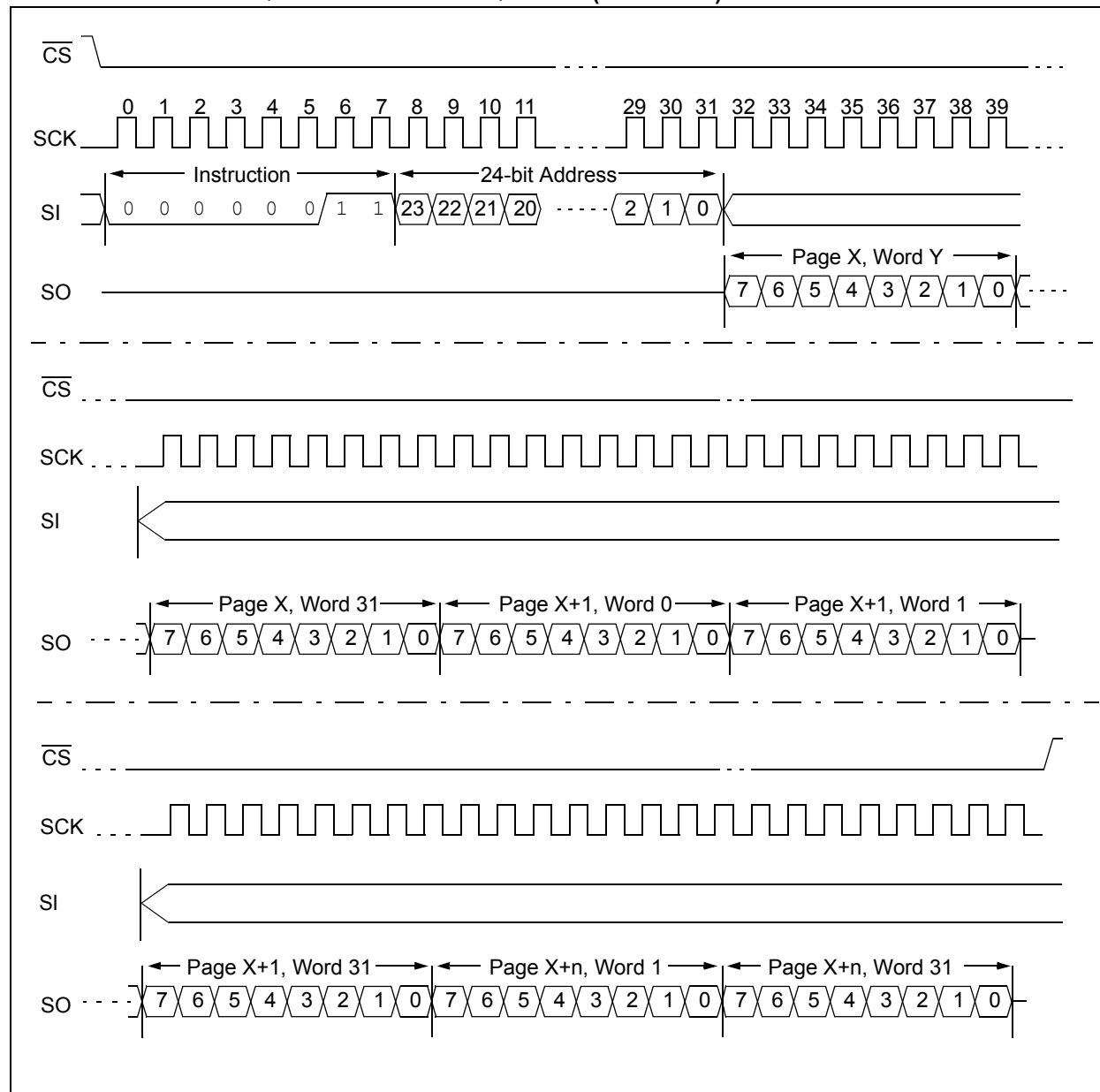
**FIGURE 2-3: PAGE READ SEQUENCE (SPI MODE)**



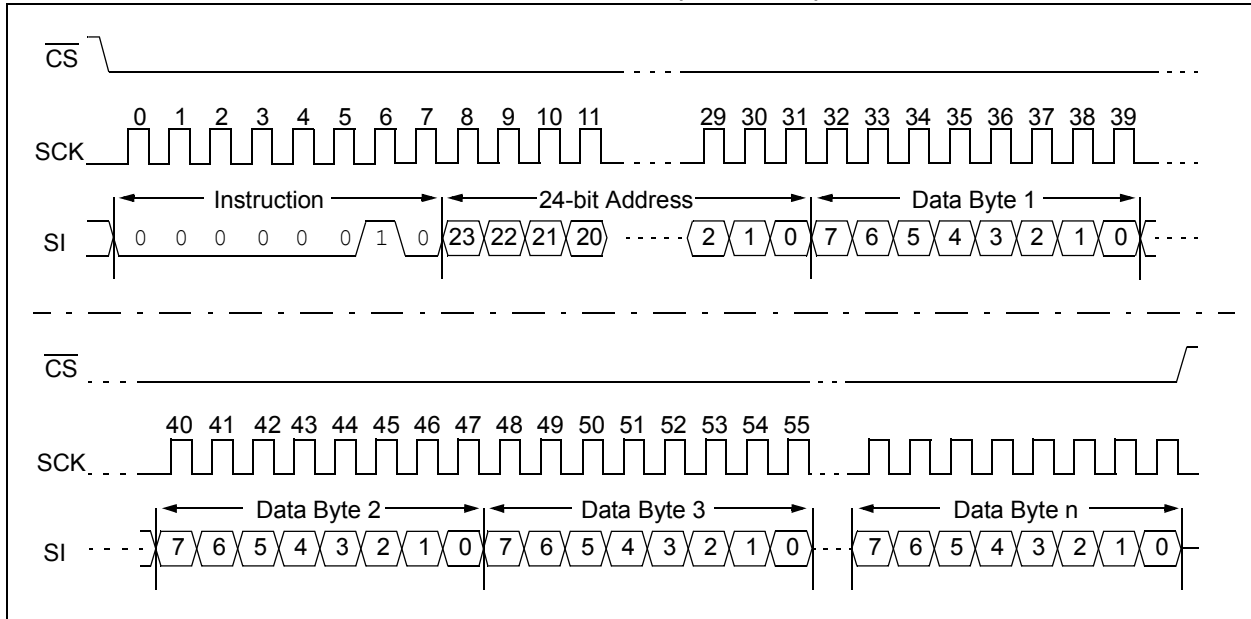
**FIGURE 2-4: PAGE WRITE SEQUENCE (SPI MODE)**



**FIGURE 2-5: SEQUENTIAL READ SEQUENCE (SPI MODE)**



**FIGURE 2-6: SEQUENTIAL WRITE SEQUENCE (SPI MODE)**



2.5 Read Mode Register Instruction (RDMR)

The Read Mode Register instruction (RDMR) provides access to the MODE register. The MODE register may be read at any time. The MODE register is formatted as follows:

TABLE 2-2: MODE REGISTER

|      |      |   |   |   |   |   |   |
|------|------|---|---|---|---|---|---|
| 7    | 6    | 5 | 4 | 3 | 2 | 1 | 0 |
| W/R  | W/R  | — | — | — | — | — | — |
| MODE | MODE | 0 | 0 | 0 | 0 | 0 | 0 |

W/R = writable/readable

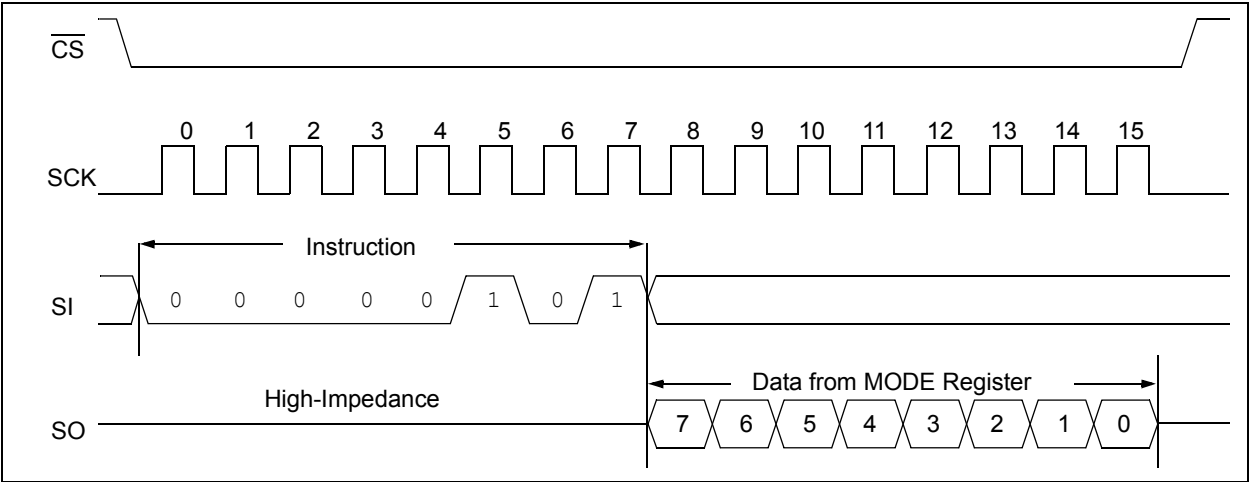
The mode bits indicate the operating mode of the SRAM. The possible modes of operation are:

- 0 0 = Byte mode
- 1 0 = Page mode
- 0 1 = Sequential mode (default operation)
- 1 1 = Reserved

Bits 0 through 5 are reserved and should always be set to '0'.

See Figure 2-7 for the RDMR timing sequence.

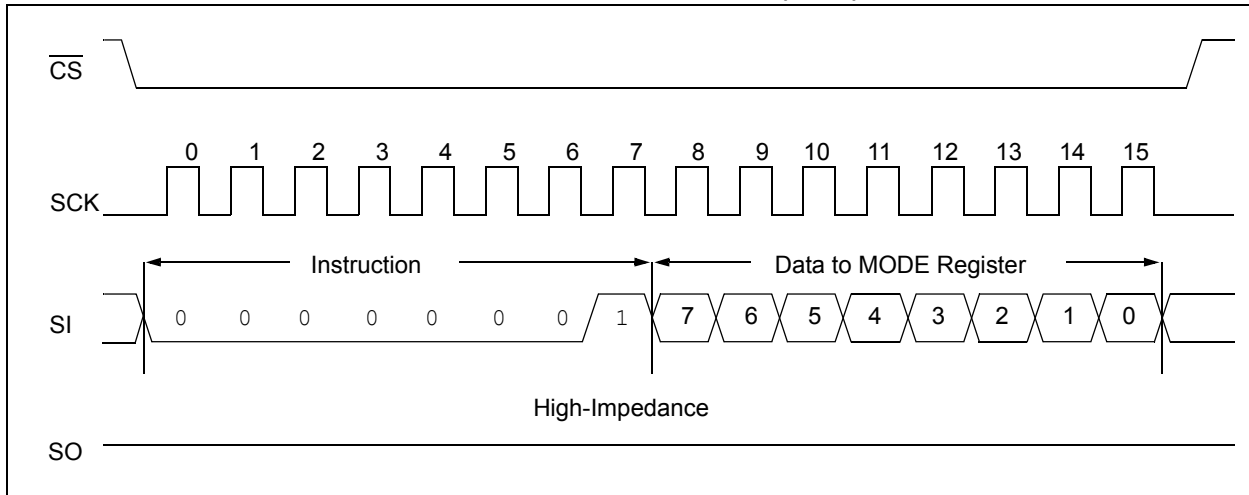
FIGURE 2-7: READ MODE REGISTER TIMING SEQUENCE (RDMR)



## 2.6 Write Mode Register Instruction (WRMR)

The Write Mode Register instruction (WRMR) allows the user to write to the bits in the MODE register as shown in Table 2-2. This allows for setting of the Device operating mode. Several of the bits in the MODE register must be cleared to '0'. See Figure 2-8 for the WRMR timing sequence.

**FIGURE 2-8: WRITE MODE REGISTER TIMING SEQUENCE (WRMR)**



## 2.7 Power-On State

The 23LCV1024 powers on in the following state:

- The device is in low-power Standby mode ( $\overline{CS} = 1$ )
- A high-to-low-level transition on  $\overline{CS}$  is required to enter active state

# 23LCV1024

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

| Name                   | SOIC/<br>PDIP<br>TSSOP | Function                   |
|------------------------|------------------------|----------------------------|
| $\overline{\text{CS}}$ | 1                      | Chip Select Input          |
| SO/SIO1                | 2                      | Serial Data Output/SDI Pin |
| NC                     | 3                      | No Connect                 |
| Vss                    | 4                      | Ground                     |
| SI/SIO0                | 5                      | Serial Data Input/SDI Pin  |
| SCK                    | 6                      | Serial Clock Input         |
| VBAT                   | 7                      | External Backup Supply     |
| Vcc                    | 8                      | Power Supply               |

### 3.1 Chip Select ( $\overline{\text{CS}}$ )

A low level on this pin selects the device. A high level deselects the device and forces it into Standby mode. When the device is deselected, SO goes to the high-impedance state, allowing multiple parts to share the same SPI bus. After power-up, a low level on  $\overline{\text{CS}}$  is required, prior to any sequence being initiated.

### 3.2 Serial Output (SO)

The SO pin is used to transfer data out of the 23LCV1024. During a read cycle, data is shifted out on this pin after the falling edge of the serial clock.

### 3.3 Serial Input (SI)

The SI pin is used to transfer data into the device. It receives instructions, addresses, and data. Data is latched on the rising edge of the serial clock.

### 3.4 Serial Dual Interface Pins(SIO0, SIO1)

The SIO0 and SIO1 pins are used for SDI mode of operation. Functionality of these I/O pins is shared with SO and SI.

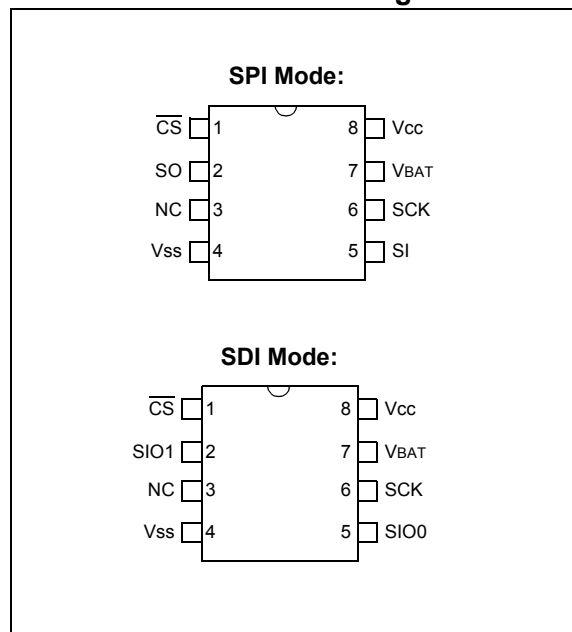
### 3.5 Serial Clock (SCK)

The SCK is used to synchronize the communication between a master and the 23LCV1024. Instructions, addresses or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

### 3.6 VBAT Supply Input

The VBAT pin is used as an input for external backup supply to maintain SRAM data when VCC is below the VTRIP point. If the VBAT function is not being used it is recommended to connect this pin to Vss.

### 3.7 SPI and SDI Pin Designations



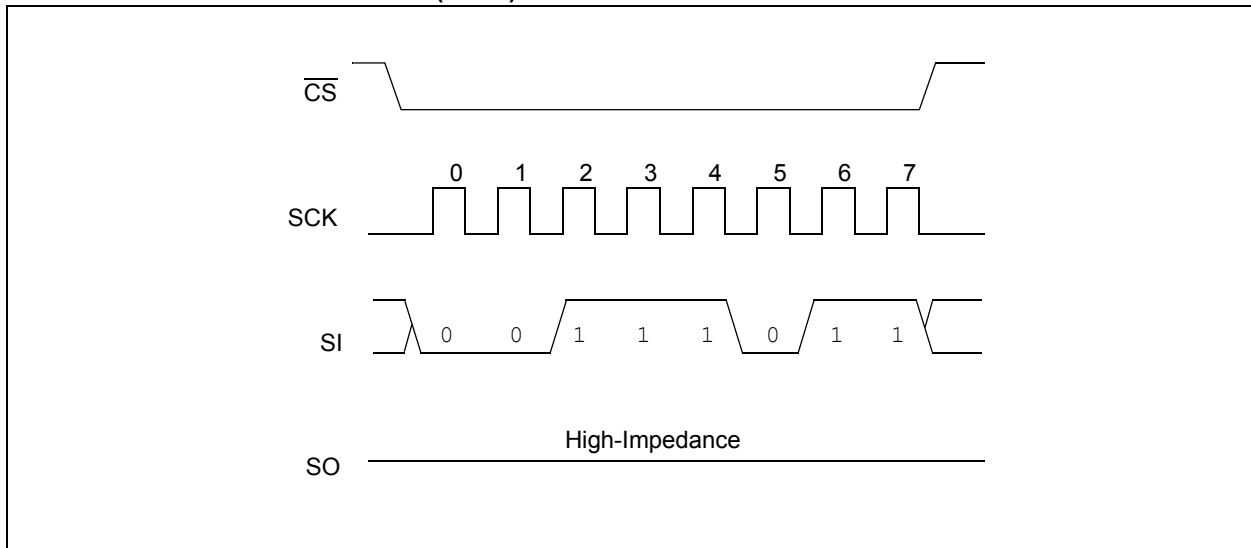
## 4.0 DUAL SERIAL MODE

The 23LCV1024 also supports SDI (Serial Dual) mode of operation when used with compatible master devices. As a convention for SDI mode of operation, two bits are entered per clock using the SIO0 and SIO1 pins. Bits are clocked MSB first.

## 4.1 Dual Interface Mode

The 23LCV1024 supports SDI (Serial Dual) mode of operation. To enter SDI mode the EDIO command must be clocked in (Figure 4-1). It should be noted that if the MCU resets before the SRAM, the user will need to determine the serial mode of operation of the SRAM and reset it accordingly. Byte read and write sequence in SDI mode is shown in Figure 4-2 and Figure 4-3.

**FIGURE 4-1: ENTER SDI MODE (EDIO) FROM SPI MODE**



**FIGURE 4-2: BYTE READ MODE SDI**

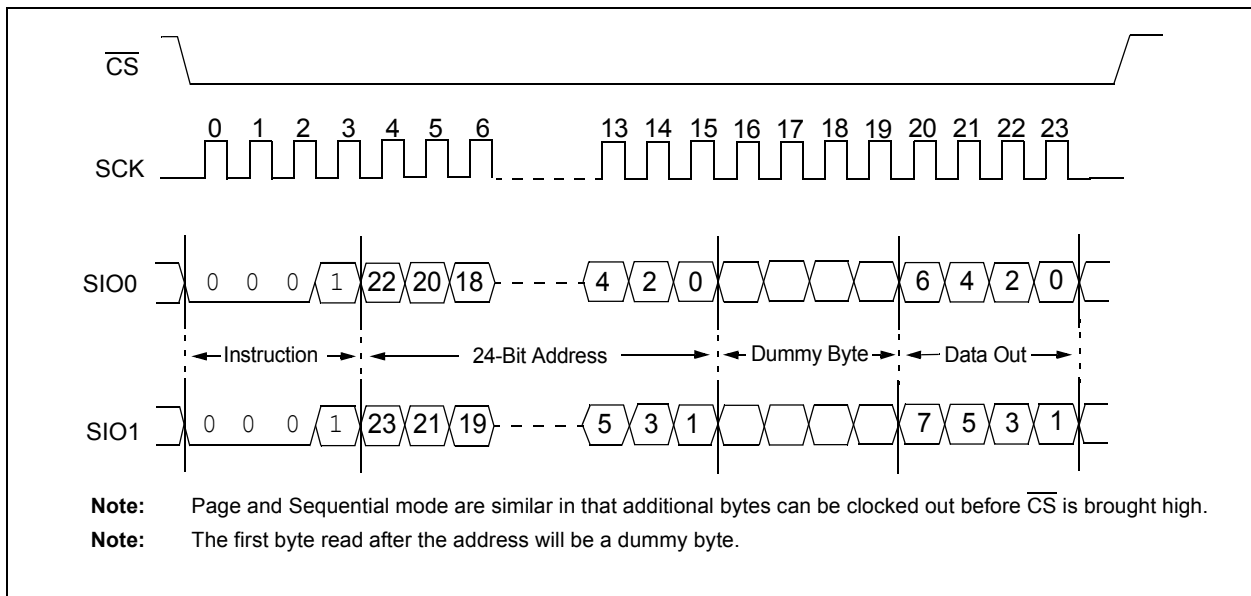
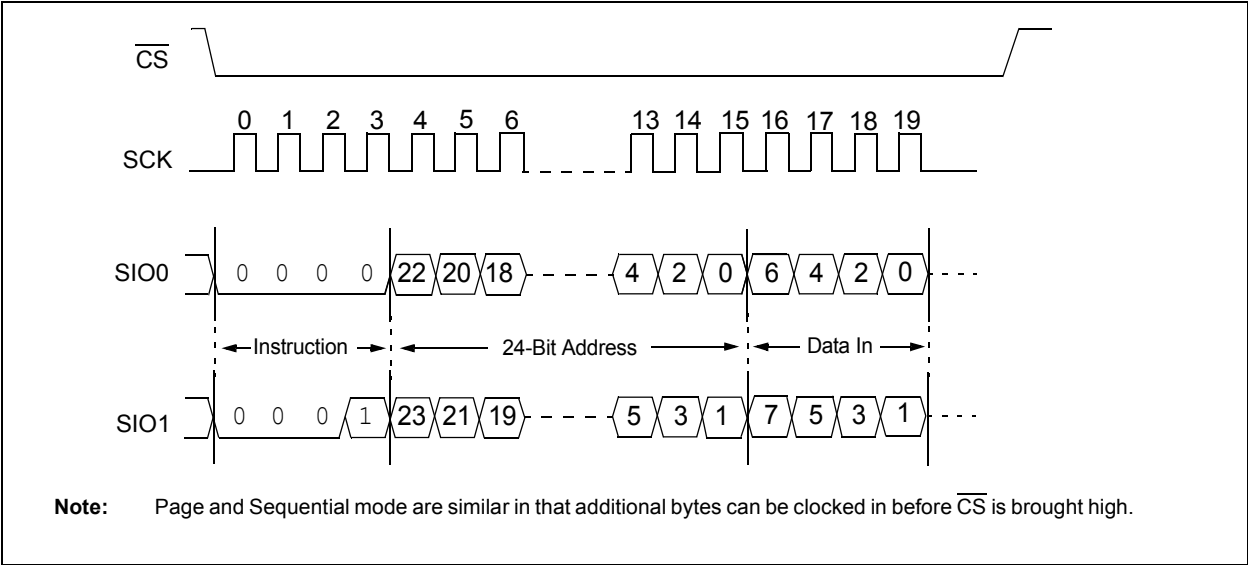


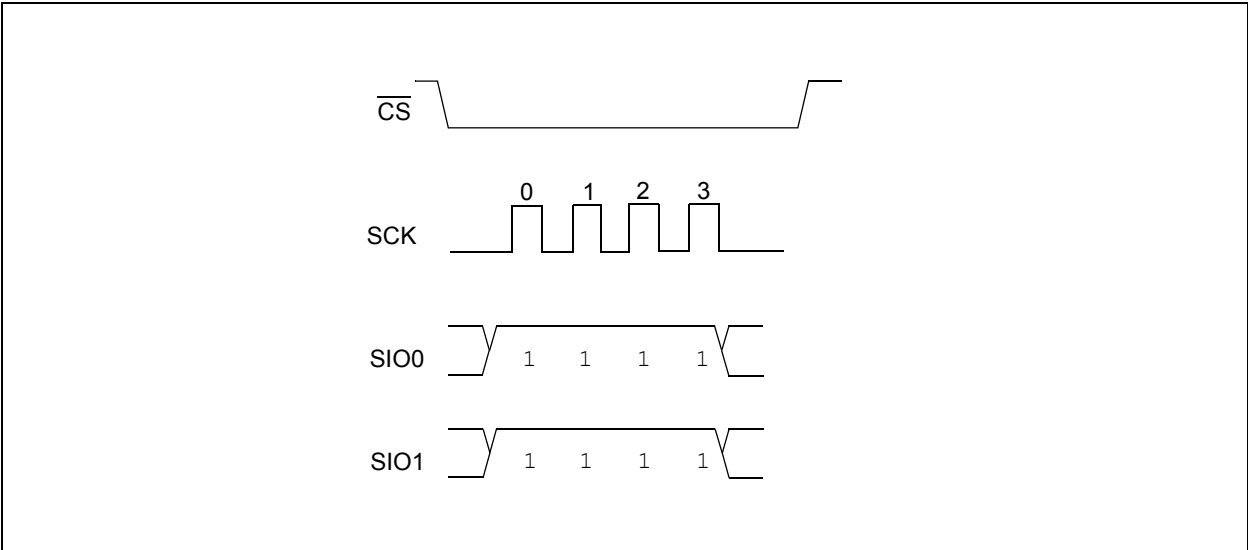
FIGURE 4-3:      BYTE WRITE MODE SDI



4.2      Exit SDI Mode

To exit from SDI mode, the RSTIO command must be issued. The command must be entered in the current device configuration see (Figure 4-4)

FIGURE 4-4:      RESET SDI MODE (RSTIO) – FROM SDI MODE



## 5.0 VBAT

The 23LCV1024 features an internal switch that will maintain the SRAM contents. In the event that the VCC supply is not available, the voltage applied to the VBAT pin serves as the backup supply.

The VBAT trip point is the point at which the internal switch operates the device from the VBAT supply and is typically 1.8V (VTRIP specification D012). When VCC falls below the VTRIP point the system will continue to maintain the SRAM contents.

The following conditions apply:

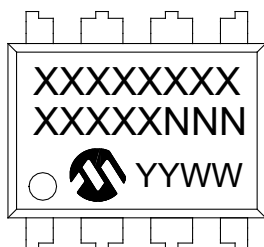
| Supply Condition        | Read/Write Access | Powered By |
|-------------------------|-------------------|------------|
| VCC < VTRIP, VCC < VBAT | No                | VBAT       |
| VCC > VTRIP, VCC < VBAT | Yes               | VCC        |
| VCC > VTRIP, VCC > VBAT | Yes               | VCC        |

# 23LCV1024

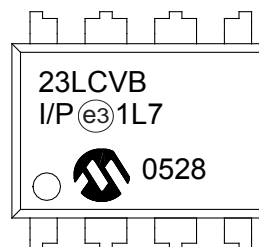
## 6.0 PACKAGING INFORMATION

### 6.1 Package Marking Information

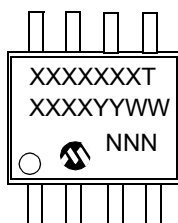
8-Lead PDIP (300 mil)



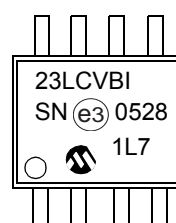
Example



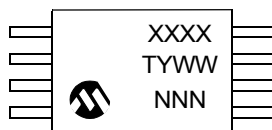
8-Lead SOIC (3.90 mm)



Example:



8-Lead TSSOP



Example:



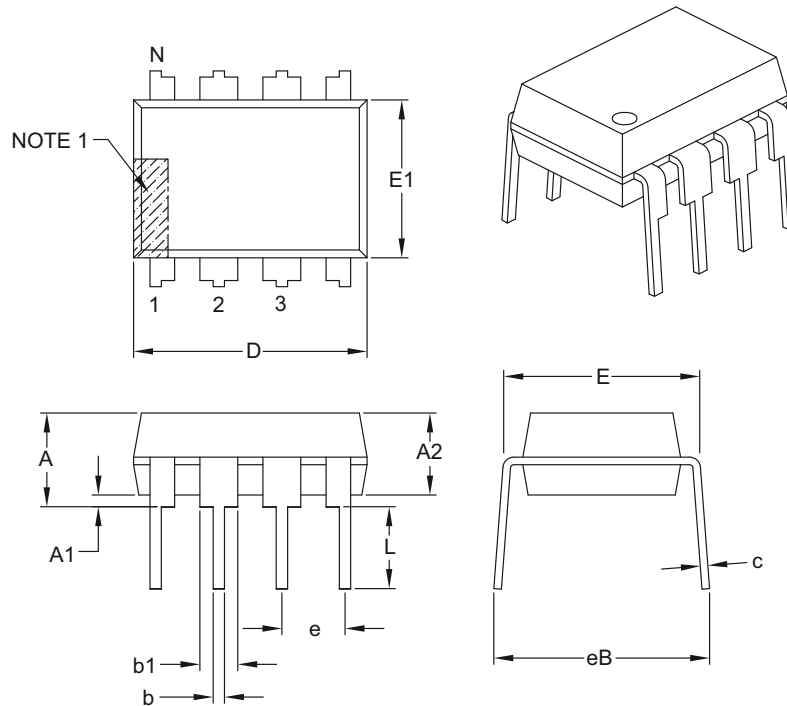
|                |        |                                                                  |
|----------------|--------|------------------------------------------------------------------|
| <b>Legend:</b> | XX...X | Part number or part number code                                  |
|                | T      | Temperature (I, E)                                               |
|                | Y      | Year code (last digit of calendar year)                          |
|                | YY     | Year code (last 2 digits of calendar year)                       |
|                | WW     | Week code (week of January 1 is week '01')                       |
|                | NNN    | Alphanumeric traceability code (2 characters for small packages) |
|                | e3     | Pb-free JEDEC designator for Matte Tin (Sn)                      |

**Note:** For very small packages with no room for the Pb-free JEDEC designator e3, the marking will only appear on the outer carton or reel label.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

## 8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Units                      |    | INCHES   |      |      |
|----------------------------|----|----------|------|------|
| Dimension Limits           |    | MIN      | NOM  | MAX  |
| Number of Pins             | N  | 8        |      |      |
| Pitch                      | e  | .100 BSC |      |      |
| Top to Seating Plane       | A  | –        | –    | .210 |
| Molded Package Thickness   | A2 | .115     | .130 | .195 |
| Base to Seating Plane      | A1 | .015     | –    | –    |
| Shoulder to Shoulder Width | E  | .290     | .310 | .325 |
| Molded Package Width       | E1 | .240     | .250 | .280 |
| Overall Length             | D  | .348     | .365 | .400 |
| Tip to Seating Plane       | L  | .115     | .130 | .150 |
| Lead Thickness             | c  | .008     | .010 | .015 |
| Upper Lead Width           | b1 | .040     | .060 | .070 |
| Lower Lead Width           | b  | .014     | .018 | .022 |
| Overall Row Spacing §      | eB | –        | –    | .430 |

### Notes:

- Pin 1 visual index feature may vary, but must be located with the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

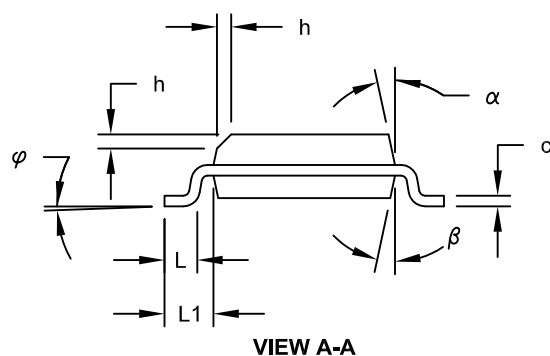
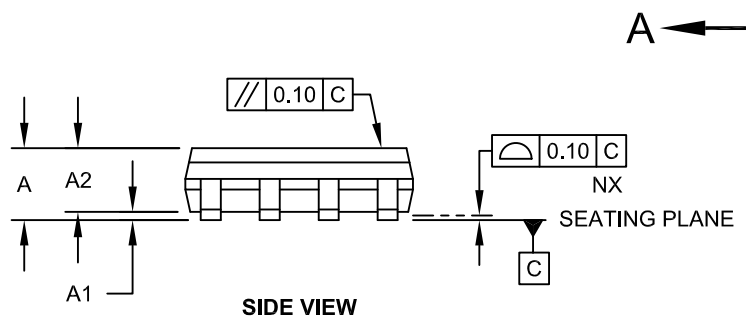
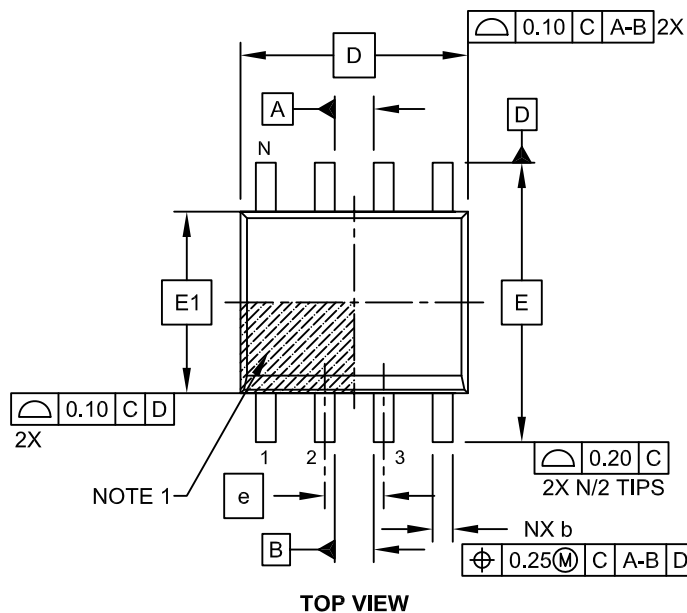
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

# 23LCV1024

## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

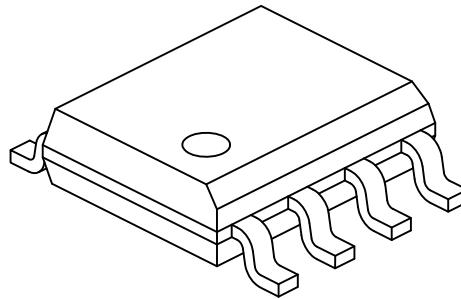
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing No. C04-057C Sheet 1 of 2

## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits         | Units | MILLIMETERS |     |      |
|--------------------------|-------|-------------|-----|------|
|                          |       | MIN         | NOM | MAX  |
| Number of Pins           | N     | 8           |     |      |
| Pitch                    | e     | 1.27 BSC    |     |      |
| Overall Height           | A     | -           | -   | 1.75 |
| Molded Package Thickness | A2    | 1.25        | -   | -    |
| Standoff §               | A1    | 0.10        | -   | 0.25 |
| Overall Width            | E     | 6.00 BSC    |     |      |
| Molded Package Width     | E1    | 3.90 BSC    |     |      |
| Overall Length           | D     | 4.90 BSC    |     |      |
| Chamfer (Optional)       | h     | 0.25        | -   | 0.50 |
| Foot Length              | L     | 0.40        | -   | 1.27 |
| Footprint                | L1    | 1.04 REF    |     |      |
| Foot Angle               | φ     | 0°          | -   | 8°   |
| Lead Thickness           | c     | 0.17        | -   | 0.25 |
| Lead Width               | b     | 0.31        | -   | 0.51 |
| Mold Draft Angle Top     | α     | 5°          | -   | 15°  |
| Mold Draft Angle Bottom  | β     | 5°          | -   | 15°  |

### Notes:

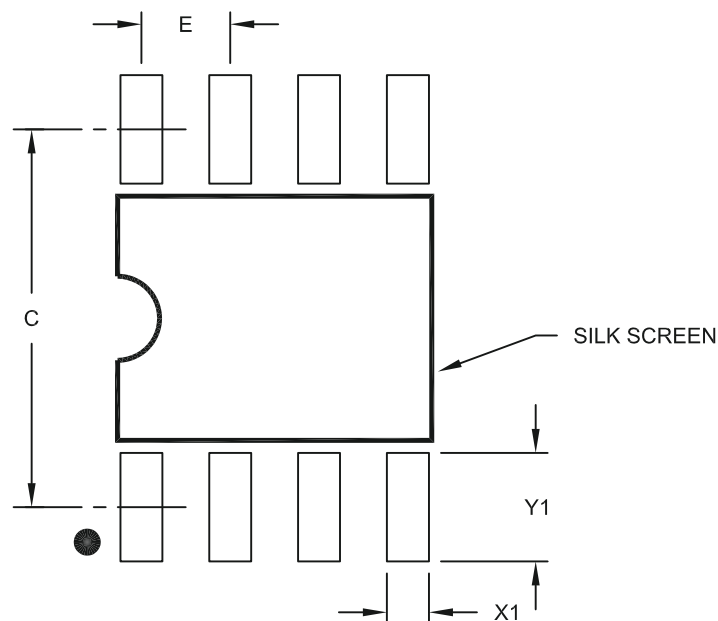
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-057C Sheet 2 of 2

# 23LCV1024

## 8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Units                   |    | MILLIMETERS |      |      |
|-------------------------|----|-------------|------|------|
| Dimension Limits        |    | MIN         | NOM  | MAX  |
| Contact Pitch           | E  | 1.27 BSC    |      |      |
| Contact Pad Spacing     | C  |             | 5.40 |      |
| Contact Pad Width (X8)  | X1 |             |      | 0.60 |
| Contact Pad Length (X8) | Y1 |             |      | 1.55 |

Notes:

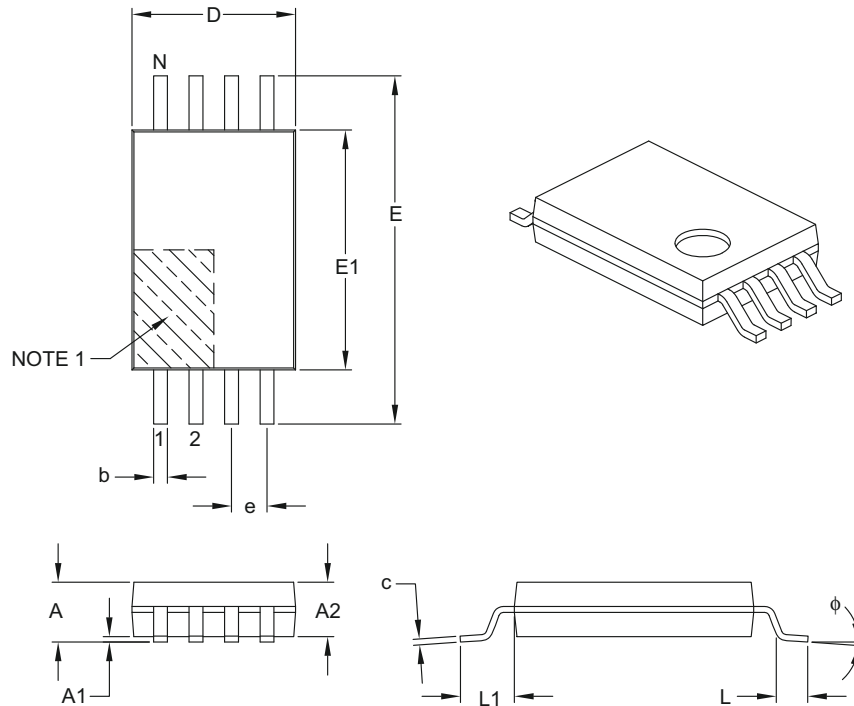
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

## 8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Units                    |    | MILLIMETERS |      |      |
|--------------------------|----|-------------|------|------|
| Dimension Limits         |    | MIN         | NOM  | MAX  |
| Number of Pins           | N  | 8           |      |      |
| Pitch                    | e  | 0.65 BSC    |      |      |
| Overall Height           | A  | –           | –    | 1.20 |
| Molded Package Thickness | A2 | 0.80        | 1.00 | 1.05 |
| Standoff                 | A1 | 0.05        | –    | 0.15 |
| Overall Width            | E  | 6.40 BSC    |      |      |
| Molded Package Width     | E1 | 4.30        | 4.40 | 4.50 |
| Molded Package Length    | D  | 2.90        | 3.00 | 3.10 |
| Foot Length              | L  | 0.45        | 0.60 | 0.75 |
| Footprint                | L1 | 1.00 REF    |      |      |
| Foot Angle               | φ  | 0°          | –    | 8°   |
| Lead Thickness           | c  | 0.09        | –    | 0.20 |
| Lead Width               | b  | 0.19        | –    | 0.30 |

### Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

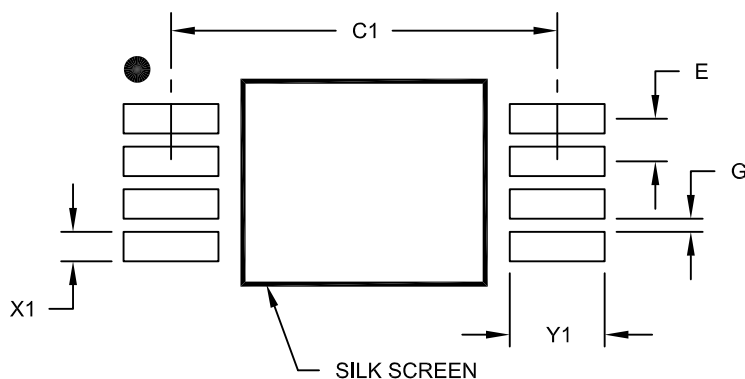
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-086B

# 23LCV1024

## 8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

| Units                   |    | MILLIMETERS |      |      |
|-------------------------|----|-------------|------|------|
| Dimension Limits        |    | MIN         | NOM  | MAX  |
| Contact Pitch           | E  | 0.65 BSC    |      |      |
| Contact Pad Spacing     | C1 |             | 5.90 |      |
| Contact Pad Width (X8)  | X1 |             |      | 0.45 |
| Contact Pad Length (X8) | Y1 |             |      | 1.45 |
| Distance Between Pads   | G  | 0.20        |      |      |

#### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2086A

## APPENDIX A: REVISION HISTORY

### Revision A (09/2012)

Initial release.

NOTES:

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|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|-------------|---|------------|------------|
| Device                                                                                                                                                                                                                                                                                                                                                                                        |  | Tape & Reel |   | Temp Range | Package    |
| <div><div><b>Device:</b>23LCV1024=1 Mbit, 2.5 - 5.5V, SPI Serial SRAM</div><div><b>Tape &amp; Reel:</b>Blank = Standard packaging (tube)<br/>T = Tape &amp; Reel</div><div><b>Temperature Range:</b>I = -40°C to +85°C</div><div><b>Package:</b>SN = Plastic SOIC (3.90 mm body), 8-lead<br/>ST = Plastic TSSOP (4.4 mm body), 8-lead<br/>P = Plastic PDIP (300 mil body), 8-lead</div></div> |  |             |   |            |            |
| <b>Examples:</b> <div>a)23LCV1024-I/ST = 1 Mbit, 2.5 - 5.5V Serial SRAM, Industrial temp., TSSOP package</div> <div>b)23LCV1024-I/SN = 1 Mbit, 2.5 - 5.5V Serial SRAM, Industrial temp., SOIC package</div> <div>c)23LCV1024-I/P = 1 Mbit, 2.5 - 5.5V Serial SRAM, Industrial temp., PDIP package</div>                                                                                       |  |             |   |            |            |

NOTES:

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